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### **PCN #152**

# Notification Date: 27 March 2015

# **Product / Process Change Notice**

#### **Parts Affected:**

Chip process CP707, PNP silicon small signal Darlington transistors, wafers, and bare die.

#### **Extent of Change:**

The CP707 wafer process has been discontinued and replaced with the CP727V wafer process.

The overall wafer diameter was increased from 4 inch to 5 inch.

The overall wafer thickness was reduced from 9 mils to 7.1 mils.

The backside metallization (Au) was reduced from 18,000Å to 9,000Å.

The die size was reduced from 27 x 27 mils to 22.8 x 22.8 mils.

The die pattern and bond pad area were changed; see figures 1 and 2 for details.

#### **Reason for Change:**

Process transfer from the 4" wafer fab to the 5" wafer fab.

#### **Effect of Change:**

This change does not affect the electrical characteristics of any device.

#### **Qualification:**

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

#### **Effective Date of Change:**

May 1, 2015. Existing inventory will be shipped until depleted.

#### **Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.

Page 1 of 2



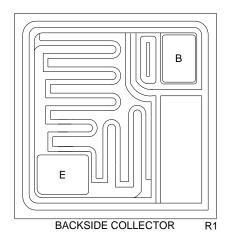
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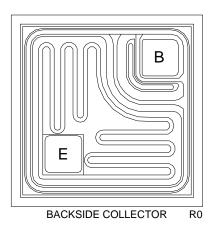
#### Figures:

#### Figure 1: CP707 Chip Geometry (Discontinued)



Wafer Diameter: 4 inch Die Size: 27 x 27 mils Die Thickness: 9.0 mils Bond Pad Size (Emitter): 5.3 x 6.5 mils Bond Pad Size (Base): 5.3 x 3.8 mils Topside Metal: AI (30,000Å) Backside Metal: Au (18,000Å)

Figure 2: CP727V Chip Geometry



Wafer Diameter: 5 inch

Die Size: 22.8 x 22.8 mils Die Thickness: 7.1 mils Bond Pad Size (Emitter): 4.7 x 4.7 mils Bond Pad Size (Base): 4.7 x 4.7 mils Topside Metal: Al-Si (17,000Å) Backside Metal: Au (9,000Å)

Part Numbers Affected:	
MPSA62	CMPTA77
MPSA63	CP707-MPSA64-WN
MPSA64	CP707-MPSU95-WN
MPSA65	CP707-CMPTA64-CTO
MPSA66	CP707-MPSU95-CT
MPSA75	
MPSA76	
MPSA77	
CXTA62	
CXTA64	
CZTA64	
CZTA77	
CEN-U95	
CMPTA63	
CMPTA64	

Page 2 of 2 R1